

(0.635 mm) .025"

MEC6-DV SERIES

VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC6-DV

Insulator Material:
Black LCP

Contact Material:
Phosphor Bronze

Plating:

Au or Sn over
50 μm (1.27 μm) Ni

Operating Temp Range:
-55 °C to +125 °C

Insertion Depth:
(4.22 mm) .166" to
(5.66 mm) .223"

Current Rating:
2.4 A per pin
(2 pins powered)

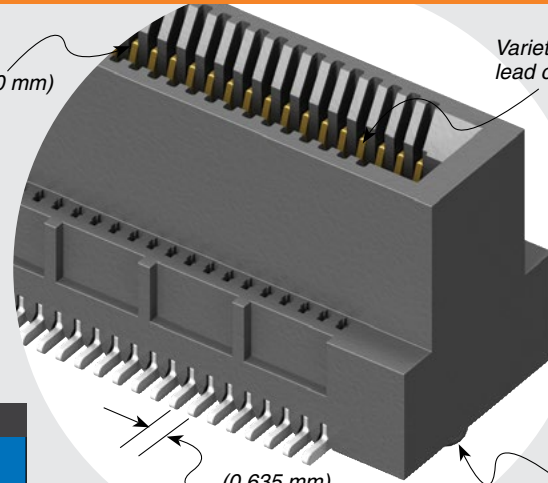
Voltage Rating:
185 VAC / 262 VDC

RoHS Compliant:
Yes

Mates with:
(1.60 mm) .062" thick card

Mates with (1.60 mm)
.062" thick card

Variety of
lead counts



Alignment pin

HIGH-SPEED CHANNEL PERFORMANCE

MEC6-DV

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

14
Gbps

PROCESSING

Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0.10 mm) .004" max (10-50)
(0.15 mm) .006" max (60-70)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality

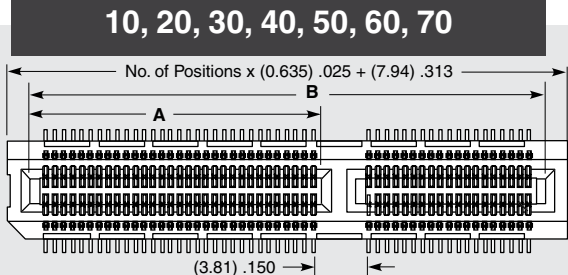


ALSO AVAILABLE (MOQ Required)

- Locking Clip
(Manual placement required)
- Other platings

Notes:
While optimized for
50 Ω applications, this
connector with alternative
signal/ground patterns may
also perform well in certain
75 Ω applications.

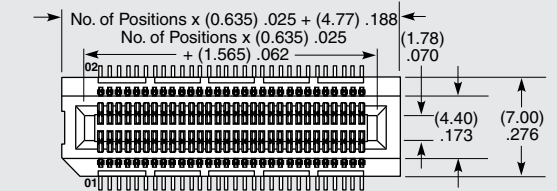
Some sizes, styles and
options are non-standard,
non-returnable.



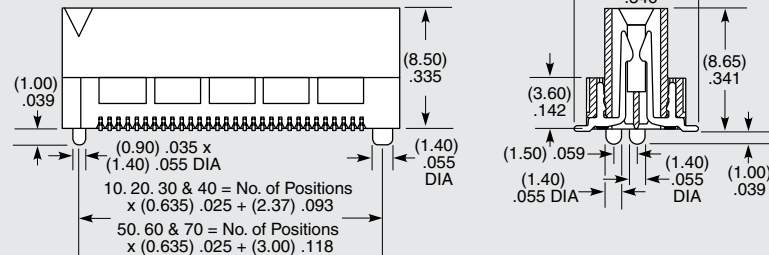
-L
= 10 μm (0.25 μm)
Gold on contact,
Matte Tin on tail

-K
= (5.50 mm) .217" DIA
Polyimide Pick
& Place Pad

-TR
= Tape & Reel



POSITIONS PER ROW	A	B
50	(21.06) .829	(36.49) 1.437
60	(24.87) .979	(42.84) 1.687
70	(28.68) 1.129	(49.19) 1.937



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.